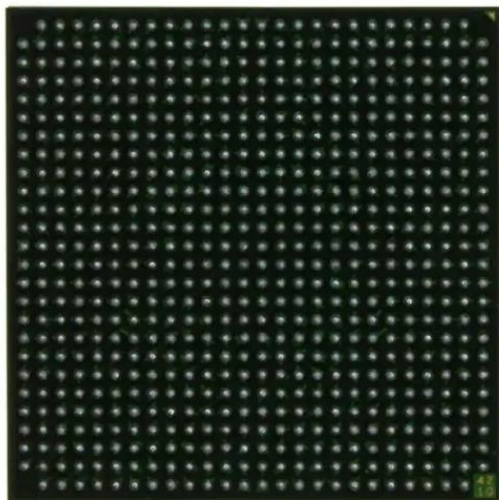




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1232
Number of Logic Elements/Cells	11088
Total RAM Bits	811008
Number of I/O	396
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FCBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp7-6ff672c



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description

DS083 (v5.0) June 21, 2011

Product Specification

Virtex-II Pro⁽¹⁾ Array Functional Description

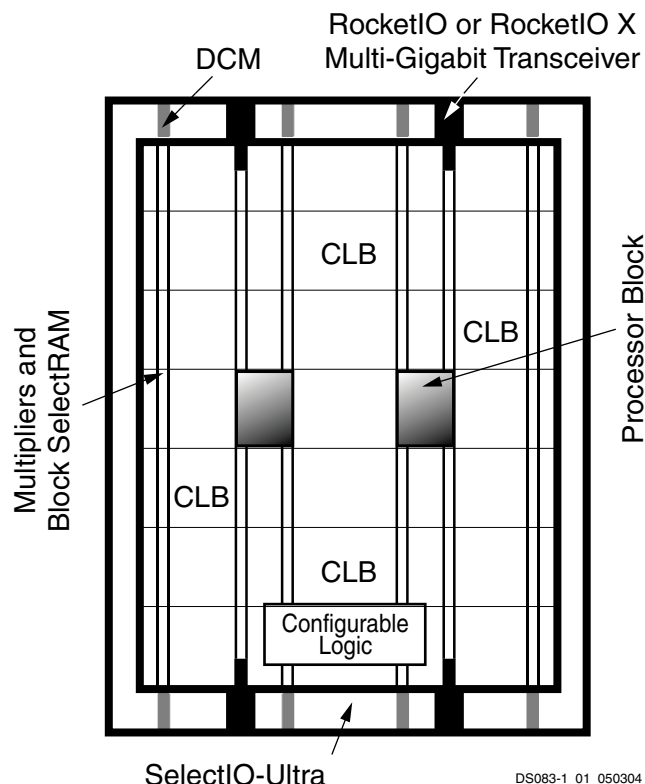


Figure 1: Virtex-II Pro Generic Architecture Overview

This module describes the following Virtex™-II Pro functional components, as shown in **Figure 1**:

- Embedded RocketIO™ (up to 3.125 Gb/s) or RocketIO X (up to 6.25 Gb/s) Multi-Gigabit Transceivers (MGTs)
- Processor blocks with embedded IBM PowerPC™ 405 RISC CPU core (PPC405) and integration circuitry.
- FPGA fabric based on Virtex-II architecture.

Virtex-II Pro User Guides

Virtex-II Pro User Guides cover theory of operation in more detail, and include implementation details, primitives and attributes, command/instruction sets, and many HDL code examples where appropriate. All parameter specifications are given only in **Module 3** of this Data Sheet.

These User Guides are available:

- For detailed descriptions of PPC405 embedded core programming models and internal core operations, see [PowerPC Processor Reference Guide](#) and [PowerPC 405 Processor Block Reference Guide](#).
- For detailed RocketIO transceiver digital/analog design considerations, see [RocketIO Transceiver User Guide](#).
- For detailed RocketIO X transceiver digital/analog design considerations, see [RocketIO X Transceiver User Guide](#).
- For detailed descriptions of the FPGA fabric (CLB, IOB, DCM, etc.), see [Virtex-II Pro Platform FPGA User Guide](#).

All of the documents above, as well as a complete listing and description of Xilinx-developed Intellectual Property cores for Virtex-II Pro, are available on the Xilinx website.

Contents of This Module

- [Functional Description: RocketIO X Multi-Gigabit Transceiver \(MGT\)](#)
- [Functional Description: RocketIO Multi-Gigabit Transceiver \(MGT\)](#)
- [Functional Description: Processor Block](#)
- [Functional Description: Embedded PowerPC 405 Core](#)
- [Functional Description: FPGA](#)
- [Revision History](#)

Virtex-II Pro Compared to Virtex-II Devices

Virtex-II Pro devices are built on the Virtex-II FPGA architecture. Most FPGA features are identical to Virtex-II devices. Major differences are described below:

- The Virtex-II Pro FPGA family is the first to incorporate embedded PPC405 and RocketIO/RocketIO X cores.
- V_{CCAUX} , the auxiliary supply voltage, is 2.5V instead of 3.3V as for Virtex-II devices. Advanced processing at 0.13 μ m has resulted in a smaller die, faster speed, and lower power consumption.
- Virtex-II Pro devices are neither bitstream-compatible nor pin-compatible with Virtex-II devices. However, Virtex-II designs can be compiled into Virtex-II Pro devices.
- On-chip input LVDS differential termination is available.
- SSTL3, AGP-2X/AGP, LVPECL_33, LVDS_33, and LVDSEXT_33 standards are not supported.
- The open-drain output pin TDO does not have an internal pull-up resistor.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Table 9: Supported Differential Signal I/O Standards

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Output V _{OD}
LDT_25	2.5	N/R	N/R	0.500 – 0.740
LVDS_25	2.5	N/R	N/R	0.247 – 0.454
LVDS_EXT_25	2.5	N/R	N/R	0.440 – 0.820
BLVDS_25	2.5	N/R	N/R	0.250 – 0.450
ULVDS_25	2.5	N/R	N/R	0.500 – 0.740
LVPECL_25	2.5	N/R	N/R	0.345 – 1.185
LDT_25_DT ⁽¹⁾	2.5	2.5	N/R	0.500 – 0.740
LVDS_25_DT ⁽¹⁾	2.5	2.5	N/R	0.247 – 0.454
LVDS_EXT_25_DT ⁽¹⁾	2.5	2.5	N/R	0.330 – 0.700
ULVDS_25_DT ⁽¹⁾	2.5	2.5	N/R	0.500 – 0.740

Notes:

1. These standards support on-chip 100Ω termination.
2. N/R = no requirement.

Table 10: Supported DCI I/O Standards

I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Termination Type
LVDCI_33 ⁽¹⁾	3.3	3.3	N/R	Series
LVDCI_25	2.5	2.5	N/R	Series
LVDCI_DV2_25	2.5	2.5	N/R	Series
LVDCI_18	1.8	1.8	N/R	Series
LVDCI_DV2_18	1.8	1.8	N/R	Series
LVDCI_15	1.5	1.5	N/R	Series
LVDCI_DV2_15	1.5	1.5	N/R	Series
GTL_DCI	1.2	1.2	0.8	Single
GTLP_DCI	1.5	1.5	1.0	Single
HSTL_I_DCI	1.5	1.5	0.75	Split
HSTL_II_DCI	1.5	1.5	0.75	Split
HSTL_III_DCI	1.5	1.5	0.9	Single
HSTL_IV_DCI	1.5	1.5	0.9	Single
HSTL_I_DCI_18	1.8	1.8	0.9	Split
HSTL_II_DCI_18	1.8	1.8	0.9	Split
HSTL_III_DCI_18	1.8	1.8	1.1	Single
HSTL_IV_DCI_18	1.8	1.8	1.1	Single
SSTL2_I_DCI ⁽²⁾	2.5	2.5	1.25	Split
SSTL2_II_DCI ⁽²⁾	2.5	2.5	1.25	Split
SSTL18_I_DCI ⁽³⁾	1.8	1.8	0.9	Split
SSTL18_II_DCI	1.8	1.8	0.9	Split

Table 10: Supported DCI I/O Standards (Continued)

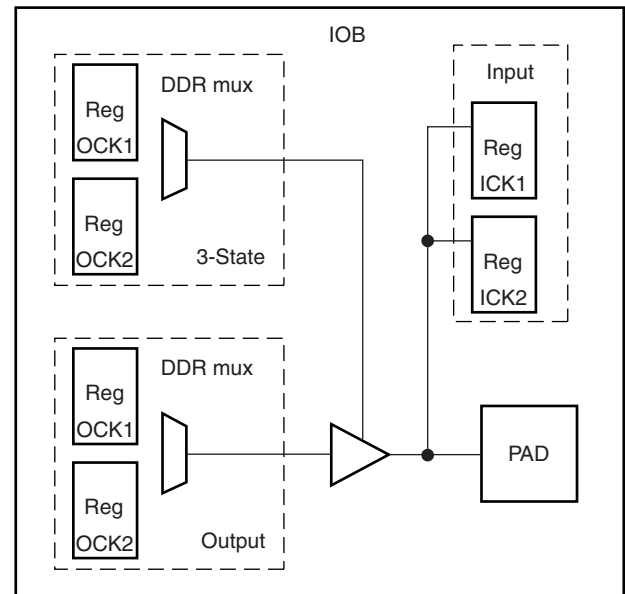
I/O Standard	Output V _{CCO}	Input V _{CCO}	Input V _{REF}	Termination Type
LVDS_25_DCI	2.5	2.5	N/R	Split
LVDS_EXT_25_DCI	2.5	2.5	N/R	Split

Notes:

1. LVDCI_XX is LVCMOS output controlled impedance buffers, matching all or half of the reference resistors.
2. These are SSTL compatible.
3. SSTL18_I is not a JEDEC-supported standard.
4. N/R = no requirement.

Logic Resources

IOB blocks include six storage elements, as shown in Figure 19.



DS031_29_100900

Figure 19: Virtex-II Pro IOB Block

Each storage element can be configured either as an edge-triggered D-type flip-flop or as a level-sensitive latch. On the input, output, and 3-state path, one or two DDR registers can be used.

Double data rate is directly accomplished by the two registers on each path, clocked by the rising edges (or falling edges) from two different clock nets. The two clock signals are generated by the DCM and must be 180 degrees out of phase, as shown in Figure 20. There are two input, output, and 3-state data signals, each being alternately clocked out.

Each block SelectRAM+ cell is a fully synchronous memory, as illustrated in Figure 48. The two ports have independent inputs and outputs and are independently clocked.

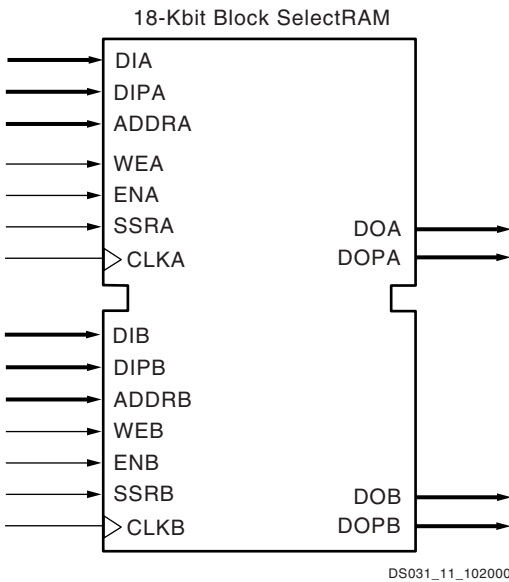


Figure 48: 18 Kb Block SelectRAM+ in Dual-Port Mode

Port Aspect Ratios

Table 23 shows the depth and the width aspect ratios for the 18 Kb block SelectRAM+ resource. Virtex-II Pro block SelectRAM+ also includes dedicated routing resources to provide an efficient interface with CLBs, block SelectRAM+, and multipliers.

Table 23: 18 Kb Block SelectRAM+ Port Aspect Ratio

Width	Depth	Address Bus	Data Bus	Parity Bus
1	16,384	ADDR[13:0]	DATA[0]	N/A
2	8,192	ADDR[12:0]	DATA[1:0]	N/A
4	4,096	ADDR[11:0]	DATA[3:0]	N/A
9	2,048	ADDR[10:0]	DATA[7:0]	Parity[0]
18	1,024	ADDR[9:0]	DATA[15:0]	Parity[1:0]
36	512	ADDR[8:0]	DATA[31:0]	Parity[3:0]

Read/Write Operations

The Virtex-II Pro block SelectRAM+ read operation is fully synchronous. An address is presented, and the read operation is enabled by control signal ENA or ENB. Then, depending on clock polarity, a rising or falling clock edge causes the stored data to be loaded into output registers.

The write operation is also fully synchronous. Data and address are presented, and the write operation is enabled by control signals WEA and WEB in addition to ENA or ENB. Then, again depending on the clock input mode, a rising or falling clock edge causes the data to be loaded into the memory cell addressed.

A write operation performs a simultaneous read operation. Three different options are available, selected by configuration:

1. WRITE_FIRST

The WRITE_FIRST option is a transparent mode. The same clock edge that writes the data input (DI) into the memory also transfers DI into the output registers DO, as shown in Figure 49.

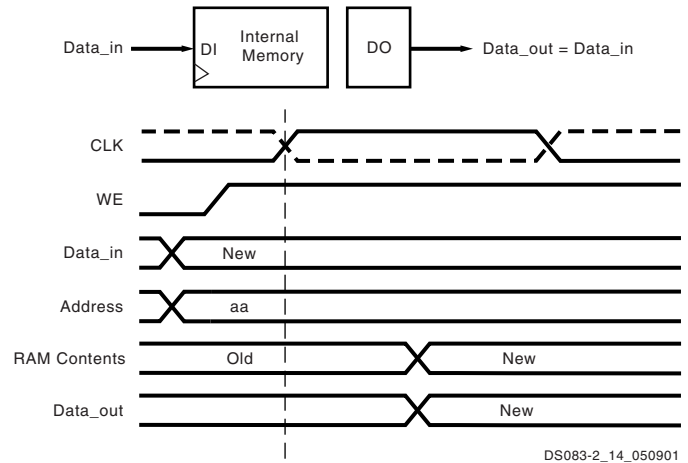


Figure 49: WRITE_FIRST Mode

2. READ_FIRST

The READ_FIRST option is a read-before-write mode.

The same clock edge that writes data input (DI) into the memory also transfers the prior content of the memory cell addressed into the data output registers DO, as shown in Figure 50.

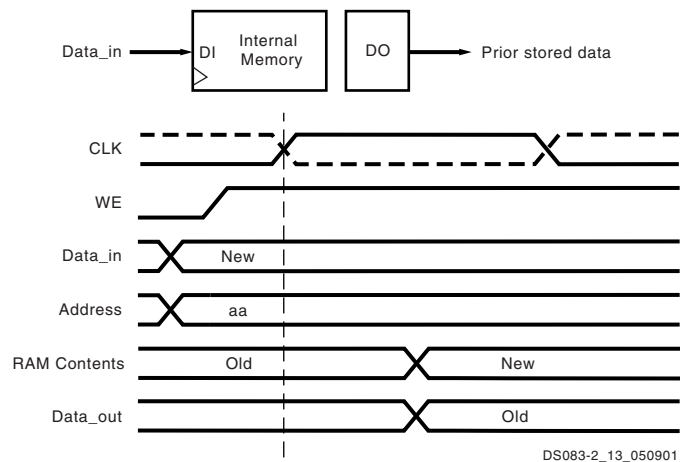


Figure 50: READ_FIRST Mode

Table 3: DC Characteristics Over Recommended Operating Conditions

Symbol	Description	Virtex-II Pro X			Virtex-II Pro			Units
		Min	Typ	Max	Min	Typ	Max	
V_{DRINT}	Data retention V_{CCINT} voltage (below which configuration data might be lost)	1.25			1.25			V
V_{DRI}	Data retention V_{CCAUX} voltage (below which configuration data might be lost)	2.0			2.0			V
I_{REF}	V_{REF} current per pin			10			10	μA
I_L	Input or output leakage current per pin (sample-tested)			10			10	μA
C_{IN}	Input capacitance (sample-tested)			10			10	pF
I_{RPU}	Pad pull-up (when selected) @ $V_{in} = 0V$, $V_{CCO} = 2.5V$ (sample tested)			150			150	μA
I_{RPD}	Pad pull-down (when selected) @ $V_{in} = 2.5V$ (sample-tested)			150			150	μA
$I_{BATT}^{(1)}$	Battery supply current	Note (2)			Note (2)			nA
I_{CCAUTX}	Operating AVCCAUTX supply current		115			60	105	mA
I_{CCAUXX}	Operating AVCCAUXRX supply current		85			35	75	mA
I_{TTX}	Operating I_{TTX} supply current when transmitter is AC-coupled		55			30		mA
	Operating I_{TTX} supply current when transmitter is DC-coupled	N/A	N/A	N/A		15		mA
I_{TRX}	Operating I_{TRX} supply current when receiver is AC-coupled		15			0		mA
	Operating I_{TRX} supply current when receiver is DC-coupled	N/A	N/A	N/A		15		
P_{CPU}	Power dissipation of PowerPC™ 405 processor block		0.9			0.9		mW/MHz
$P_{RXTX}^{(3)}$	Power dissipation of MGT @ 1.25 Gb/s per channel	N/A	N/A	N/A		230		mW
	Power dissipation of MGT @ 2.5 Gb/s per channel		290			310		mW
	Power dissipation of MGT @ 3.125 Gb/s per channel		310			350		mW
	Power dissipation of MGT @ 4.25 Gb/s per channel		450		N/A	N/A	N/A	mW
	Power dissipation of MGT @ 6.25 Gb/s per channel		525		N/A	N/A	N/A	mW

Notes:

1. Characterized, not tested.
2. Battery supply current (I_{BATT}):

	Device Unpowered	Device Powered	Units
25°C:	< 50	< 10	nA
85°C:	N/A	< 10	nA

3. Total dissipation of fully operational PMA and PCS combined. This power is the average power supply dissipation per MGT. The averaging was done by simultaneously turning on all eight transceivers and dividing the total power supply dissipation by eight.

Output Clock Jitter

Table 59: Output Clock Jitter

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Clock Synthesis Period Jitter						
CLK0	CLKOUT_PER_JITT_0		±100	±100	±100	ps
CLK90	CLKOUT_PER_JITT_90		±150	±150	±150	ps
CLK180	CLKOUT_PER_JITT_180		±150	±150	±150	ps
CLK270	CLKOUT_PER_JITT_270		±150	±150	±150	ps
CLK2X, CLK2X180	CLKOUT_PER_JITT_2X		±200	±200	±200	ps
CLKDV (integer division)	CLKOUT_PER_JITT_DV1		±150	±150	±150	ps
CLKDV (non-integer division)	CLKOUT_PER_JITT_DV2		±300	±300	±300	ps
CLKFX, CLKFX180	CLKOUT_PER_JITT_FX		Note (1)	Note (1)	Note (1)	ps

Notes:

1. Use the **Jitter Calculator** on the Xilinx website (http://www.xilinx.com/applications/web_ds_v2/jitter_calc.htm) for CLKFX and CLKFX180 output jitter.

Output Clock Phase Alignment

Table 60: Output Clock Phase Alignment

Description	Symbol	Constraints	Speed Grade			Units
			–7	–6	–5	
Phase Offset Between CLKIN and CLKFB						
CLKIN/CLKFB	CLKIN_CLKFB_PHASE		±50	±50	±50	ps
Phase Offset Between Any DCM Outputs						
All CLK* outputs	CLKOUT_PHASE		±140	±140	±140	ps
Duty Cycle Precision						
DLL outputs ⁽¹⁾	CLKOUT_DUTY_CYCLE_DLL ⁽²⁾		±150	±150	±150	ps
CLKFX outputs	CLKOUT_DUTY_CYCLE_FX		±100	±100	±100	ps

Notes:

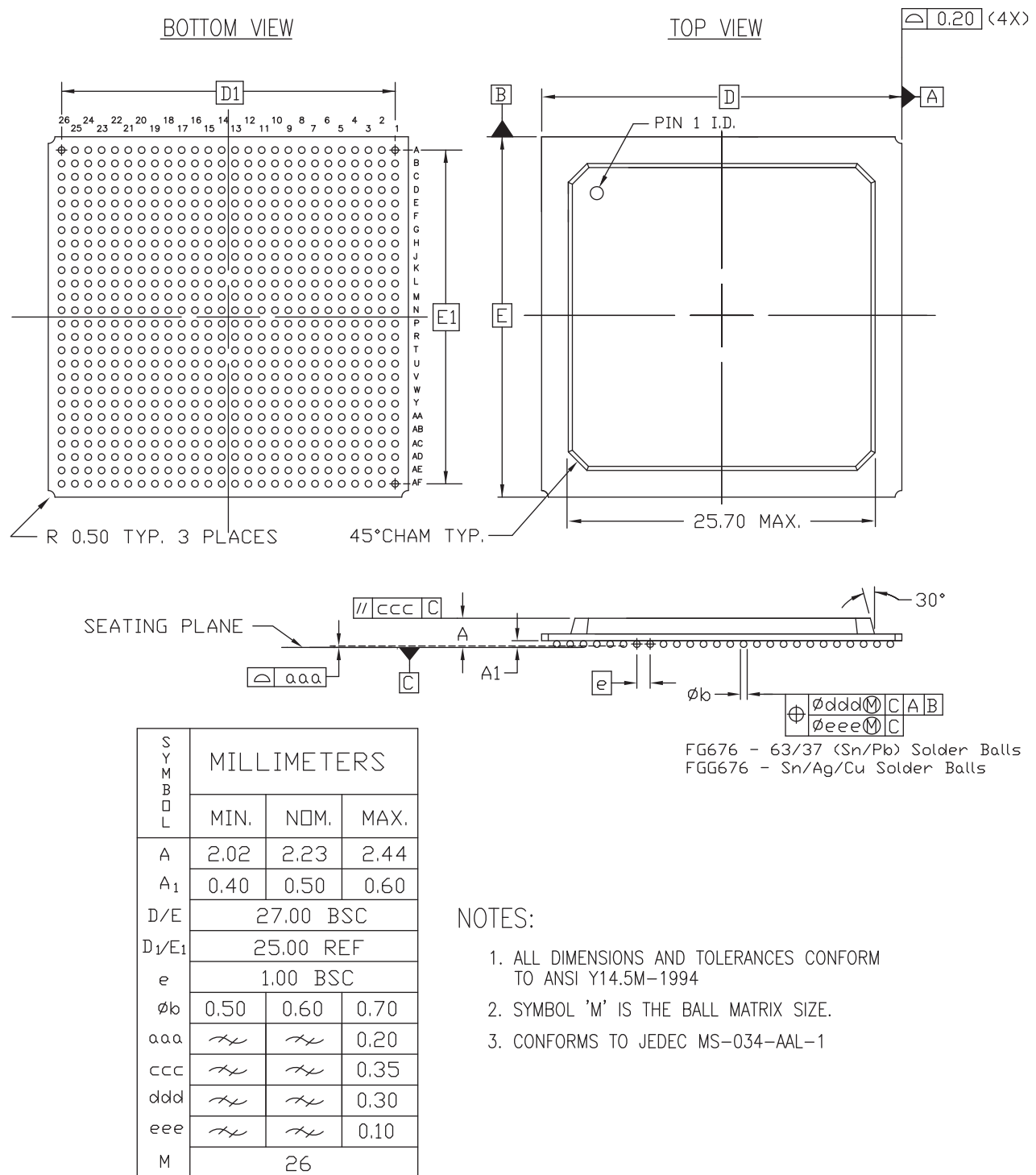
1. “DLL outputs” is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. CLKOUT_DUTY_CYCLE_DLL applies to the 1X clock outputs (CLK0, CLK90, CLK180, and CLK270) only if DUTY_CYCLE_CORRECTION = TRUE.
3. Specification also applies to PSCLK.

Date	Version	Revision
12/05/03 (cont'd)	3.0 (cont'd)	- Non-speedsfile parameter values added or updated: Table 3: I_{BATT}. Table 4: For XC2VP100, I_{CCINTQ}, I_{CCOQ}, and I_{CCAUXQ}. Table 5: For XC2VP100, $I_{CCINTMIN}$. Table 17: T_{CPWL} and T_{CPWH}. Table 25: Added explanatory footnote to T_{RXLAT} (MGT receiver latency) max value. Table 57: Added Footnote (3) regarding use of CLKIN_DIVIDE_BY_2 attribute.
02/19/04	3.1	- Updated time and frequency parameters as per speedsfile v1.85. Table 2, Recommended Operating Conditions: Revised Footnotes (4) and (6). Table 4, Quiescent Supply Current: Added Footnote (1) and updated Typical parameters. Table 10, LVPECL DC Specifications: Added parameter values for Maximum Differential Input Voltage (LVPECL). Table 14, Register-to-Register Performance: Removed reference to a number of designs for which test data is no longer provided. Table 16, Processor Clocks Absolute AC Characteristics: Added Footnote (1) referring to XAPP755. - Added Table 41, Clock Distribution Switching Characteristics. - Revised section Configuration Timing, page 39 through page 41, and JTAG Test Access Port Switching Characteristics, page 42, with improved timing diagrams, parameter tables, and organization. Table 50, Master/Slave Serial Mode Timing Characteristics, and Table 51, SelectMAP Mode Write Timing Characteristics: Added parameter $F_{CC_STARTUP}$. Table 51, SelectMAP Mode Write Timing Characteristics: Broke out T_{SMDCC}/T_{SMCCD}, DATA[0:7] setup/hold time, by device, and added new parameter specifications for XC2VP70 and XC2VP100 devices. Table 57, Operating Frequency Ranges: Added callouts for existing Footnote (3) to the four CLKIN parameters. Added new Footnote (4) to the four CLKIN parameters. Added new Footnote (5) to CLK2X, CLK2X180. Added new Footnote (6) to CLK2X, CLK2X180; CLK0, CLK180; and CLKIN (using DLL outputs).
03/09/04	3.1.1	Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
04/22/04	3.2	Table 2, Recommended Operating Conditions: Corrected VTTX/VTRX lower voltage limit from 1.8V to 1.6V. Table 5, Power-On Current for Virtex-II Pro Devices: Added Footnote (2) stating that listed I_{CCOMIN} values apply to the entire device (all banks). Table 40, Output Delay Measurement Methodology: Corrected V_{MEAS} for LVTTTL from 1.4V to 1.65V. Table 57, Operating Frequency Ranges: Corrected CLKOUT_FREQ_1X_LF_MAX and CLKIN_FREQ_DLL_LF_MAX for -7 devices from 210 MHz to 270 MHz. Table 65, Package Skew: Removed XC2VP40FF1517.
06/30/04	4.0	Merged in DS110-3 (Module 3 of Virtex-II Pro X data sheet). This merge added numerous previously unpublished RocketIO X MGT parameters. Specifications in this revision are from speedsfile v1.86 .

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VCCAUX	L1			
N/A	VCCAUX	B21			
N/A	VCCAUX	B2			
N/A	VCCAUX	AB11			
N/A	VCCAUX	AA21			
N/A	VCCAUX	AA2			
N/A	VCCAUX	A12			
N/A	GND	Y3			
N/A	GND	Y20			
N/A	GND	W4			
N/A	GND	W19			
N/A	GND	V5			
N/A	GND	V18			
N/A	GND	P9			
N/A	GND	P14			
N/A	GND	P13			
N/A	GND	P12			
N/A	GND	P11			
N/A	GND	P10			
N/A	GND	N9			
N/A	GND	N14			
N/A	GND	N13			
N/A	GND	N12			
N/A	GND	N11			
N/A	GND	N10			
N/A	GND	M9			
N/A	GND	M14			
N/A	GND	M13			
N/A	GND	M12			
N/A	GND	M11			
N/A	GND	M10			
N/A	GND	M1			
N/A	GND	L9			
N/A	GND	L22			
N/A	GND	L14			
N/A	GND	L13			
N/A	GND	L12			

FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch)



ds083_4_03_053111

Figure 3: FG676/FGG676 Fine-Pitch BGA Package Specifications

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
3	IO_L90N_3	P2			
3	IO_L90P_3	P3			
3	IO_L89N_3	P4			
3	IO_L89P_3	P5			
3	IO_L88N_3	P6			
3	IO_L88P_3	P7			
3	IO_L87N_3/VREF_3	R1			
3	IO_L87P_3	R2			
3	IO_L86N_3	R3			
3	IO_L86P_3	R4			
3	IO_L85N_3	R5			
3	IO_L85P_3	R6			
3	IO_L60N_3	P8	NC		
3	IO_L60P_3	R8	NC		
3	IO_L59N_3	T1	NC		
3	IO_L59P_3	T2	NC		
3	IO_L58N_3	T3	NC		
3	IO_L58P_3	T4	NC		
3	IO_L57N_3/VREF_3	T5	NC		
3	IO_L57P_3	T6	NC		
3	IO_L56N_3	R7	NC		
3	IO_L56P_3	T7	NC		
3	IO_L55N_3	T8	NC		
3	IO_L55P_3	U7	NC		
3	IO_L54N_3	U1	NC		
3	IO_L54P_3	V1	NC		
3	IO_L53N_3	U3	NC		
3	IO_L53P_3	U4	NC		
3	IO_L52N_3	U5	NC		
3	IO_L52P_3	U6	NC		
3	IO_L51N_3/VREF_3	V2	NC		
3	IO_L51P_3	V3	NC		
3	IO_L50N_3	V4	NC		
3	IO_L50P_3	V5	NC		
3	IO_L49N_3	V6	NC		
3	IO_L49P_3	V7	NC		

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R17			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U10			
N/A	GND	U12			
N/A	GND	U13			
N/A	GND	U14			
N/A	GND	U15			
N/A	GND	U17			
N/A	GND	Y20			
N/A	GND	AA21			
N/A	GND	AB22			
N/A	GND	AC23			
N/A	GND	AD24			

Notes:

1. See [Table 4](#) for an explanation of the signals available on this pin.

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	VCCINT		Y13			
N/A	VCCINT		Y12			
N/A	VCCINT		W20			
N/A	VCCINT		W11			
N/A	VCCINT		V20			
N/A	VCCINT		V11			
N/A	VCCINT		U20			
N/A	VCCINT		U11			
N/A	VCCINT		T20			
N/A	VCCINT		T11			
N/A	VCCINT		R20			
N/A	VCCINT		R11			
N/A	VCCINT		P20			
N/A	VCCINT		P11			
N/A	VCCINT		N20			
N/A	VCCINT		N11			
N/A	VCCINT		M20			
N/A	VCCINT		M11			
N/A	VCCINT		L19			
N/A	VCCINT		L18			
N/A	VCCINT		L17			
N/A	VCCINT		L16			
N/A	VCCINT		L15			
N/A	VCCINT		L14			
N/A	VCCINT		L13			
N/A	VCCINT		L12			
N/A	GND		AK22			
N/A	GND		AK9			
N/A	GND		AJ29			
N/A	GND		AJ2			
N/A	GND		AH28			
N/A	GND		AH17			
N/A	GND		AH14			
N/A	GND		AH3			
N/A	GND		AG27			
N/A	GND		AG22			

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
7	VCCO_7	T23				
7	VCCO_7	U23				
N/A	CCLK	AE9				
N/A	PROG_B	J26				
N/A	DONE	AE10				
N/A	M0	AF26				
N/A	M1	AE26				
N/A	M2	AE25				
N/A	TCK	J9				
N/A	TDI	H28				
N/A	TDO	H7				
N/A	TMS	K10				
N/A	PWRDWN_B	AF9				
N/A	HSWAP_EN	K25				
N/A	RSVD	G8				
N/A	VBATT	K9				
N/A	DXP	K26				
N/A	DXN	G27				
N/A	AVCCAUXTX2	B32	NC	NC		
N/A	VTTXPAD2	B33	NC	NC		
N/A	TXNPAD2	A33	NC	NC		
N/A	TXPPAD2	A32	NC	NC		
N/A	GND A2	C30	NC	NC		
N/A	RXPPAD2	A31	NC	NC		
N/A	RXNPAD2	A30	NC	NC		
N/A	VTRXPAD2	B31	NC	NC		
N/A	AVCCAUXRX2	B30	NC	NC		
N/A	AVCCAUXTX4	B28				
N/A	VTTXPAD4	B29				
N/A	TXNPAD4	A29				
N/A	TXPPAD4	A28				
N/A	GND A4	C27				
N/A	RXPPAD4	A27				
N/A	RXNPAD4	A26				
N/A	VTRXPAD4	B27				
N/A	AVCCAUXRX4	B26				
N/A	AVCCAUXTX5	B24	NC	NC	NC	

FF1148 Flip-Chip Fine-Pitch BGA Package

As shown in [Table 11](#), XC2VP40 and XC2VP50 Virtex-II Pro devices are available in the FF1148 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for the differences shown in the No Connect column. Following this table are the [FF1148 Flip-Chip Fine-Pitch BGA Package Specifications \(1.00mm pitch\)](#).

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
0	IO_L01N_0/VRP_0	E25		
0	IO_L01P_0/VRN_0	F25		
0	IO_L02N_0	J24		
0	IO_L02P_0	K24		
0	IO_L03N_0	C25		
0	IO_L03P_0/VREF_0	D25		
0	IO_L05_0/No_Pair	G25		
0	IO_L06N_0	A25		
0	IO_L06P_0	B25		
0	IO_L07N_0	G24		
0	IO_L07P_0	G23		
0	IO_L08N_0	H23		
0	IO_L08P_0	H22		
0	IO_L09N_0	E24		
0	IO_L09P_0/VREF_0	F24		
0	IO_L19N_0	C24		
0	IO_L19P_0	C23		
0	IO_L20N_0	J23		
0	IO_L20P_0	K23		
0	IO_L21N_0	A24		
0	IO_L21P_0	B24		
0	IO_L25N_0	E23		
0	IO_L25P_0	F23		
0	IO_L26N_0	K22		
0	IO_L26P_0	L22		
0	IO_L27N_0	D23		
0	IO_L27P_0/VREF_0	D22		
0	IO_L37N_0	A23		
0	IO_L37P_0	B23		
0	IO_L38N_0	J21		
0	IO_L38P_0	J20		
0	IO_L39N_0	F22		
0	IO_L39P_0	G22		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L59P_2	U11		
2	IO_L60N_2	R1		
2	IO_L60P_2	R2		
2	IO_L85N_2	T3		
2	IO_L85P_2	T4		
2	IO_L86N_2	U8		
2	IO_L86P_2	U9		
2	IO_L87N_2	U2		
2	IO_L87P_2	T2		
2	IO_L88N_2/VREF_2	U4		
2	IO_L88P_2	U5		
2	IO_L89N_2	U6		
2	IO_L89P_2	U7		
2	IO_L90N_2	V3		
2	IO_L90P_2	U3		
3	IO_L90N_3	V6		
3	IO_L90P_3	V7		
3	IO_L89N_3	V10		
3	IO_L89P_3	V11		
3	IO_L88N_3	V4		
3	IO_L88P_3	V5		
3	IO_L87N_3/VREF_3	V2		
3	IO_L87P_3	W2		
3	IO_L86N_3	V8		
3	IO_L86P_3	V9		
3	IO_L85N_3	W6		
3	IO_L85P_3	W7		
3	IO_L60N_3	W3		
3	IO_L60P_3	W4		
3	IO_L59N_3	W10		
3	IO_L59P_3	W11		
3	IO_L58N_3	Y5		
3	IO_L58P_3	Y6		
3	IO_L57N_3/VREF_3	Y3		
3	IO_L57P_3	AA3		
3	IO_L56N_3	W8		
3	IO_L56P_3	Y7		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
4	IO_L47N_4	AE15		
4	IO_L47P_4	AD15		
4	IO_L48N_4	AM14		
4	IO_L48P_4	AL14		
4	IO_L49N_4	AP14		
4	IO_L49P_4	AN14		
4	IO_L50_4/No_Pair	AH15		
4	IO_L53_4/No_Pair	AG16		
4	IO_L54N_4	AK15		
4	IO_L54P_4	AJ15		
4	IO_L55N_4	AM15		
4	IO_L55P_4	AL16		
4	IO_L56N_4	AE16		
4	IO_L56P_4	AD16		
4	IO_L57N_4	AP15		
4	IO_L57P_4/VREF_4	AN15		
4	IO_L66N_4	AJ16	NC	
4	IO_L66P_4/VREF_4	AH16	NC	
4	IO_L67N_4	AN16		
4	IO_L67P_4	AM16		
4	IO_L68N_4	AG17		
4	IO_L68P_4	AF17		
4	IO_L69N_4	AJ17		
4	IO_L69P_4/VREF_4	AH17		
4	IO_L73N_4	AL17		
4	IO_L73P_4	AK17		
4	IO_L74N_4/GCLK3S	AE17		
4	IO_L74P_4/GCLK2P	AD17		
4	IO_L75N_4/GCLK1S	AN17		
4	IO_L75P_4/GCLK0P	AM17		
5	IO_L75N_5/GCLK7S	AM18		
5	IO_L75P_5/GCLK6P	AN18		
5	IO_L74N_5/GCLK5S	AD18		
5	IO_L74P_5/GCLK4P	AE18		
5	IO_L73N_5	AK18		
5	IO_L73P_5	AL18		
5	IO_L69N_5/VREF_5	AH18		

FF1517 Flip-Chip Fine-Pitch BGA Package

As shown in [Table 12](#), XC2VP50 and XC2VP70 Virtex-II Pro devices are available in the FF1517 flip-chip fine-pitch BGA package. Following this table are the [FF1517 Flip-Chip Fine-Pitch BGA Package Specifications \(1.00mm pitch\)](#).

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L01N_0/VRP_0	D31		
0	IO_L01P_0/VRN_0	E31		
0	IO_L02N_0	K30		
0	IO_L02P_0	J30		
0	IO_L03N_0	G30		
0	IO_L03P_0/VREF_0	H30		
0	IO_L05_0/No_Pair	K28		
0	IO_L06N_0	E30		
0	IO_L06P_0	F30		
0	IO_L07N_0	C30		
0	IO_L07P_0	D30		
0	IO_L08N_0	J29		
0	IO_L08P_0	K29		
0	IO_L09N_0	G29		
0	IO_L09P_0/VREF_0	H29		
0	IO_L19N_0	E29		
0	IO_L19P_0	F29		
0	IO_L20N_0	L28		
0	IO_L20P_0	L27		
0	IO_L21N_0	C29		
0	IO_L21P_0	D29		
0	IO_L25N_0	H28		
0	IO_L25P_0	J28		
0	IO_L26N_0	M27		
0	IO_L26P_0	M26		
0	IO_L27N_0	D28		
0	IO_L27P_0/VREF_0	E28		
0	IO_L28N_0	H27	NC	
0	IO_L28P_0	J27	NC	
0	IO_L29N_0	J26	NC	
0	IO_L29P_0	K26	NC	
0	IO_L30N_0	F28	NC	
0	IO_L30P_0	G27	NC	
0	IO_L34N_0	D27	NC	

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND	Y34		
N/A	GND	AU32		
N/A	GND	AN32		
N/A	GND	G32		
N/A	GND	C32		
N/A	GND	AH31		
N/A	GND	AD31		
N/A	GND	T31		
N/A	GND	M31		
N/A	GND	Y30		
N/A	GND	AU28		
N/A	GND	AN28		
N/A	GND	G28		
N/A	GND	C28		
N/A	GND	AT24		
N/A	GND	AN24		
N/A	GND	AJ24		
N/A	GND	AC24		
N/A	GND	AB24		
N/A	GND	AA24		
N/A	GND	Y24		
N/A	GND	W24		
N/A	GND	V24		
N/A	GND	U24		
N/A	GND	L24		
N/A	GND	G24		
N/A	GND	D24		
N/A	GND	AD23		
N/A	GND	AC23		
N/A	GND	AB23		
N/A	GND	AA23		
N/A	GND	Y23		
N/A	GND	W23		
N/A	GND	V23		
N/A	GND	U23		
N/A	GND	T23		
N/A	GND	AD22		
N/A	GND	AU39		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L03P_7		D37		
7	IO_L03N_7		E37		
7	IO_L02P_7		D36		
7	IO_L02N_7		E36		
7	IO_L01P_7/VRN_7		C37		
7	IO_L01N_7/VRP_7		C38		
0	VCCO_0		D25		
0	VCCO_0		G23		
0	VCCO_0		G28		
0	VCCO_0		G32		
0	VCCO_0		J25		
0	VCCO_0		J29		
0	VCCO_0		P22		
0	VCCO_0		P23		
0	VCCO_0		P24		
0	VCCO_0		P25		
0	VCCO_0		P26		
0	VCCO_0		R22		
0	VCCO_0		R23		
0	VCCO_0		R24		
0	VCCO_0		R25		
1	VCCO_1		R21		
1	VCCO_1		R20		
1	VCCO_1		R19		
1	VCCO_1		R18		
1	VCCO_1		P21		
1	VCCO_1		P20		
1	VCCO_1		P19		
1	VCCO_1		P18		
1	VCCO_1		P17		
1	VCCO_1		J18		
1	VCCO_1		J14		
1	VCCO_1		G20		
1	VCCO_1		G15		
1	VCCO_1		G11		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	IO_L40P_2	R5	
2	IO_L41N_2	V6	
2	IO_L41P_2	V7	
2	IO_L42N_2	R3	
2	IO_L42P_2	P3	
2	IO_L43N_2	R1	
2	IO_L43P_2	R2	
2	IO_L44N_2	W10	
2	IO_L44P_2	W11	
2	IO_L45N_2	T7	
2	IO_L45P_2	R7	
2	IO_L46N_2/VREF_2	T4	
2	IO_L46P_2	T5	
2	IO_L47N_2	W9	
2	IO_L47P_2	Y10	
2	IO_L48N_2	T1	
2	IO_L48P_2	T2	
2	IO_L49N_2	U6	
2	IO_L49P_2	T6	
2	IO_L50N_2	W7	
2	IO_L50P_2	Y8	
2	IO_L51N_2	U4	
2	IO_L51P_2	T3	
2	IO_L52N_2/VREF_2	U2	
2	IO_L52P_2	U3	
2	IO_L53N_2	Y11	
2	IO_L53P_2	Y12	
2	IO_L54N_2	V4	
2	IO_L54P_2	V5	
2	IO_L55N_2	V1	
2	IO_L55P_2	V2	
2	IO_L56N_2	Y6	
2	IO_L56P_2	Y7	
2	IO_L57N_2	W5	
2	IO_L57P_2	W6	
2	IO_L58N_2/VREF_2	W3	
2	IO_L58P_2	V3	

Date	Version	Revision
11/17/04	4.1	Table 4: Added requirement to V_{BATT} to connect pin to V_{CCAUX} or GND if battery is not used.
03/01/05	4.2	Table 3: Corrected number of Differential I/O Pairs for XC2VP30-FF1152 from 340 to 316. Table 4: Changed Direction for User I/O pins (IO_LXXY_#) from “Input/Output” to “Input/Output/Bidirectional”.
06/20/05	4.3	<i>No changes in Module 4 for this revision.</i>
09/15/05	4.4	<i>No changes in Module 4 for this revision.</i>
10/10/05	4.5	<i>No changes in Module 4 for this revision.</i>
03/05/07	4.6	Figure 2, page 29: Corrected NOTE 3. Figure 7, page 161: Updated with drawing showing correct heat sink profile and detail.
11/05/07	4.7	Updated copyright notice and legal disclaimer.
06/21/11	5.0	Added <i>Product Not Recommended for New Designs</i> banner. Updated Figure 3, page 50 , with the newest FG676/FGG676 mechanical drawing.

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Virtex-II Pro Data Sheet

The Virtex-II Pro Data Sheet contains the following modules:

- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview (Module 1)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description (Module 2)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics (Module 3)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information (Module 4)